



06-07-2004



102759631 PATENTS ONLY

Form PTO-1595 (Rev. 10/02) OMB No. 0651-0027 (exp. 6/30/2005)

RECORDED

DEPARTMENT OF COMMERCE Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): HATA, Shohei SOTOKAWA, Hideo FURUICHI, Hiroaki 6/1/04 Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies) Name: HITACHI, LTD. Street Address: 6, Kanda Surugadai, 4-chome, Chiyoda-ku, Tokyo, Japan

3. Nature of conveyance: Assignment Security Agreement Other _____ Merger Change of Name Execution Date: March 1, 8, 2004

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: _____. A. Patent Application No.(s) 10/786,106 Filed February 26, 2004

B. Patent Registration No.(s) Additional number(s) attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Antonelli, Terry, Stout & Kraus, LLP Internal Address: 1300 North Seventeenth Street Suite 1800 Arlington, VA 22209 USA City: _____ State: _____ Zip: _____

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41)..... \$ 40.00 Enclosed Authorized to be charged to deposit account

8. Deposit account number: 01-2135 (Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William J. Solomon Reg#28,565 Name of Person Signing

Signature

06/01/04 Date

Total number of pages including cover sheet, attachments, and document: 2

Mall documents to be recorded with required cover sheet information to: Commissioner of Patent & Trademarks, Box Assignments Washington, D.C. 20231

06/03/2004 ARONDAF1 00000080 10786106 02 FC:8021 40.00 OP

PATENT REEL: 015408 FRAME: 0957

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ANODIC BONDING METHOD AND ELECTRONIC DEVICE HAVING ANODIC BONDING STRUCTURE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1)	<u>Shohei Hata</u>	<u>March 1, 2004</u>
2)	<u>Yideo Sotokawa</u>	<u>March 8, 2004</u>
3)	<u>Yiroaki Furuchi</u>	<u>March 8, 2004</u>
4)	_____	_____
5)	_____	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____